506211894 08/19/2020

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6258637

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SUNG HO CHO	08/11/2020

RECEIVING PARTY DATA

Name:	SK HYNIX INC.	
Street Address:	treet Address: 2091, GYEONGCHUNG-DAERO, BUBAL-EUB	
City:	ity: ICHEON-SI GYEONGGI-DO	
State/Country: KOREA, REPUBLIC OF		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16997623

CORRESPONDENCE DATA

Fax Number: (630)323-0335

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: uspto.actions@wpapat.com

Correspondent Name: WILLIAM PARK & ASSOCIATES LTD.

Address Line 1: 930 N. YORK ROAD, SUITE 201

Address Line 4: HINSDALE, ILLINOIS 60521

ATTORNEY DOCKET NUMBER:	NEY DOCKET NUMBER: PA4270-0	
NAME OF SUBMITTER: W. WILLIAM PARK		
SIGNATURE:	/W. William Park/	
DATE SIGNED:	08/19/2020	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 1

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PATENT 506211894 REEL: 053543 FRAME: 0044

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING EMBEDDED SOLDER CONNECTION STRUCTURE		
Declaration	As the below named inventor(s), I hereby declare that: The declaration is directed to: The attached application, or United States application or PCT international application number PCT/KR####################################		
Assignment	NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s) SK hynix Inc. 2091, Gyeongchung-daero, Bubal-eub Icheon-si Gyeonggi-do, 17336, Republic of Korea and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreigig countries any and all improvements thereof, the entire rights, title and interest in and to any and all Patents which may be granted therefore in the United States. (Hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in and to the same, for his sole use and for the use of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made. I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary. I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale. I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will testify as to the same in any litigation related thereto and will promptly execute and deliver		
Legal Name Of Inventor	Inventor Name (First Middle LAST):	Sung He CHO	
	Inventor Signature:	Sung Ho Cho	
	Date:	11. AUG-, 2020	

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A total of ___ supplemental sheet(s) are attached hereto for additional inventors, if any.